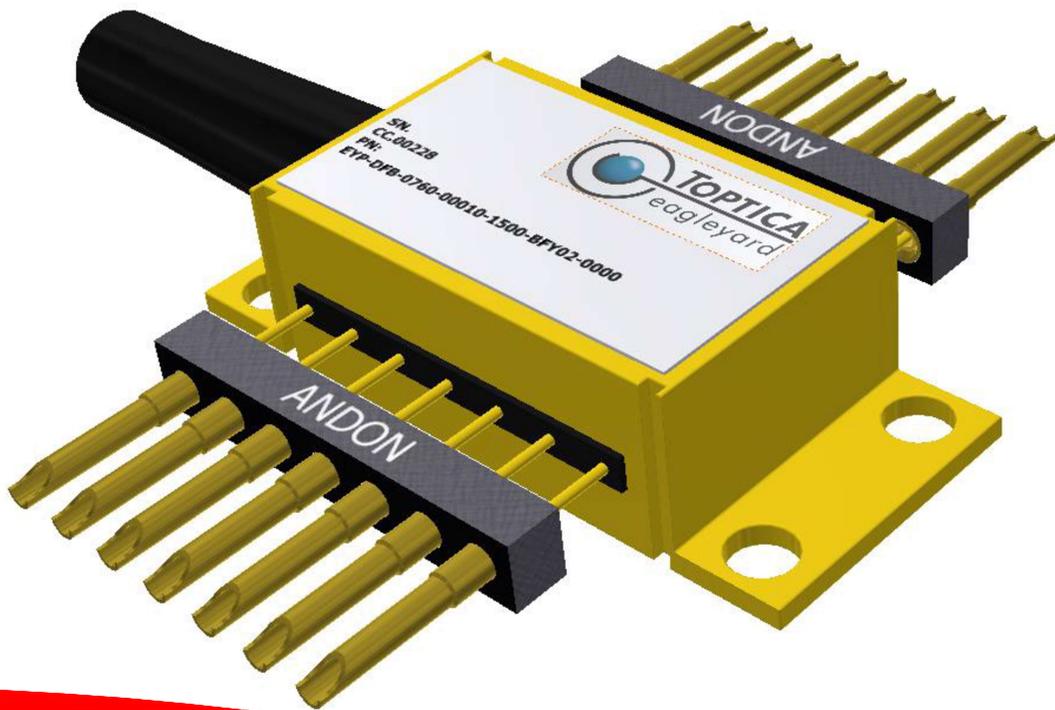




High-Reliability Optoelectronic Sockets for Toptica eagleyard



Featuring Andon's Unique SenstacTM Contact

Toptica eagleyard							
Toptica eagleyard Model Number "xxxx" stands for specific Product Type	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type		Pin Ø [in]	Figure Number	Page Number	
		Thru-Hole	Surface Mount				
SINGLE MODE LASER DIODES	EYP-RWL-xxxx-xxxxx-xxxx-BFW02-xxxx	(2) C10-007-07-01-556S-R27-L14	-	-	.018	3	1
	EYP-RWL-xxxx-xxxxx-xxxx-TOSxx-xxxx	R080-0403-01N-XXX-R27-L14	274K	281K	.018	4	2
	EYP-RWL-xxxx-xxxxx-xxxx-SOTxx-xxxx	R100-0403-04N-XXX-R27-L14	75S	265S	.018	1	1
SINGLE FREQUENCY LASER DIODES	EYP-DFB-xxxx-xxxxx-xxxx-BFYxx-xxxx	(2) C10-007-07-01-556S-R27-L14	-	-	.018	3	1
	EYP-DFB-xxxx-xxxxx-xxxx-BFWxx-xxxx	(2) C10-007-07-01-556S-R27-L14	-	-	.018	3	1
	EYP-DFB-xxxx-xxxxx-xxxx-SOTxx-xxxx	R100-0403-04N-XXX-R27-L14	75S	265S	.018	1	1
	EYP-DFB-xxxx-xxxxx-xxxx-TOCxx-xxxx	F500-SP09-01-XXX-R27-L14	433E	285E	.040	2	1
	EYP-DFB-xxxx-xxxxx-xxxx-TOVxx-xxxx	R200-0808-01T-XXX-R27-L14	75S	265S	.018	5	2
	EYP-DBR-xxxx-xxxxx-xxxx-TOCxx-xxxx	F500-SP09-01-XXX-R27-L14	433E	295E	.040	2	1
	EYP-DBR-xxxx-xxxxx-xxxx-BFYxx-xxxx	(2) C10-007-07-01-556S-R27-L14	-	-	.018	3	1
	EYP-DBR-xxxx-xxxxx-xxxx-BFWxx-xxxx	(2) C10-007-07-01-556S-R27-L14	-	-	.018	3	1
	EYP-RWS-xxxx-xxxxx-xxxx-SOTxx-xxxx	R100-0403-04N-XXX-R27-L14	75S	265S	.018	1	1
	EYP-RWS-xxxx-xxxxx-xxxx-TOSxx-xxxx	R080-0403-01N-XXX-R27-L14	274K	281K	.018	4	2
	EYP-RWS-xxxx-xxxxx-xxxx-TOVxx-xxxx	R200-0808-01T-XXX-R27-L14	75S	265S	.018	5	2
	BROAD AREA LASER DIODES	EYP-BAL-xxxx-xxxxx-xxxx-SOTxx-xxxx	R100-0403-04N-XXX-R27-L14	75S	265S	.018	1
GAIN CHIPS	EYP-RWE-xxxx-xxxxx-xxxx-SOTxx-xxxx	R100-0403-04N-XXX-R27-L14	75S	265S	.018	1	1

Heat sink socket available to reduce heat and noise. Contact Andon for details.

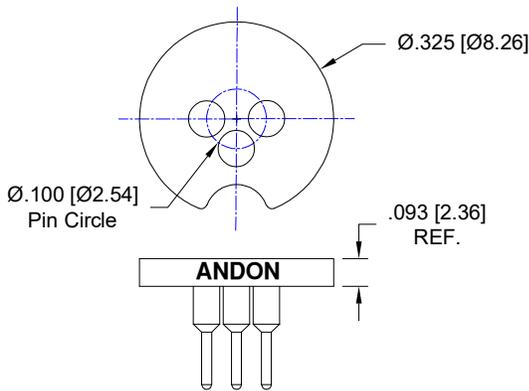


Fig. 1

Thru-Hole: R100-0403-04N-75S-R27-L14
Surface Mount: R100-0403-04N-265S-R27-L14

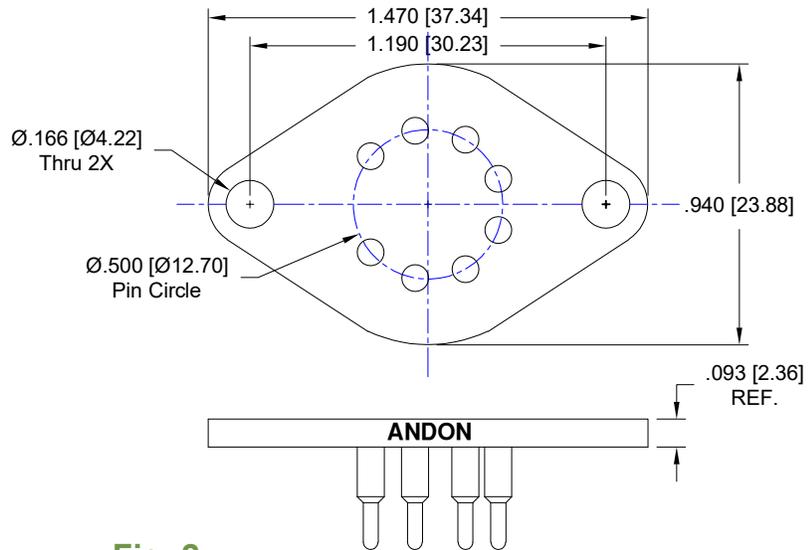


Fig. 2

Thru-Hole: F500-SP09-01-433E-R27-L14
Surface Mount: F500-SP09-01-285E-R27-L14

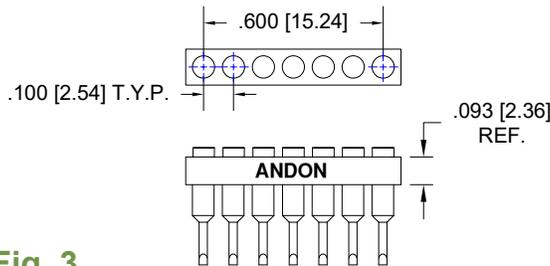


Fig. 3

Solder Cup: (2) C10-007-07-01-556S-R27-L14

Toptica eagleyard Continued
Socket Terminal Details
Cross Section View Shown Units: in [mm]

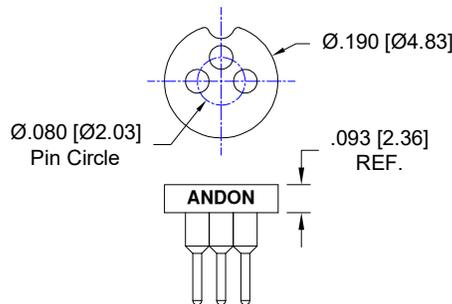


Fig. 4
Thru-Hole: R080-0403-01N-274K-R27-L14
Surface Mount: R080-0403-01N-281K-R27-L14

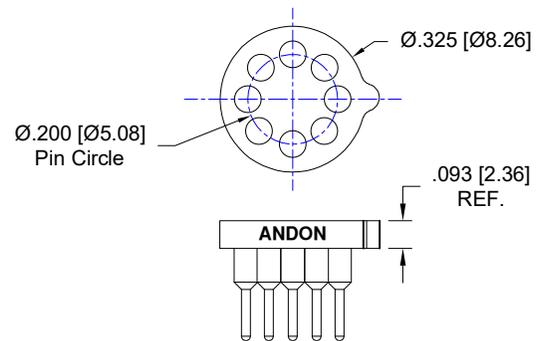
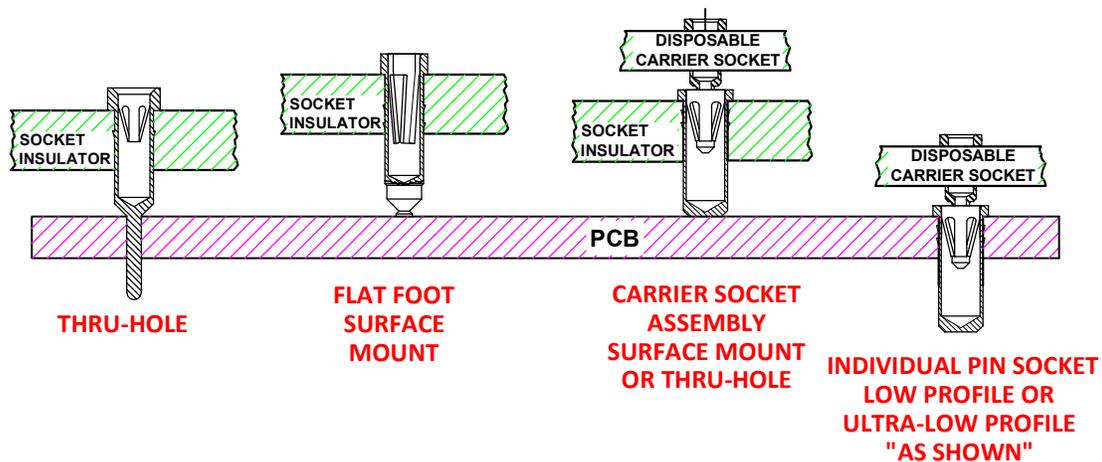


FIG: 5
Thru-Hole: R200-0808-01T-75S-R27-L14
Surface Mount: R200-0808-01T-265S-R27-L14

Socket Mounting Options



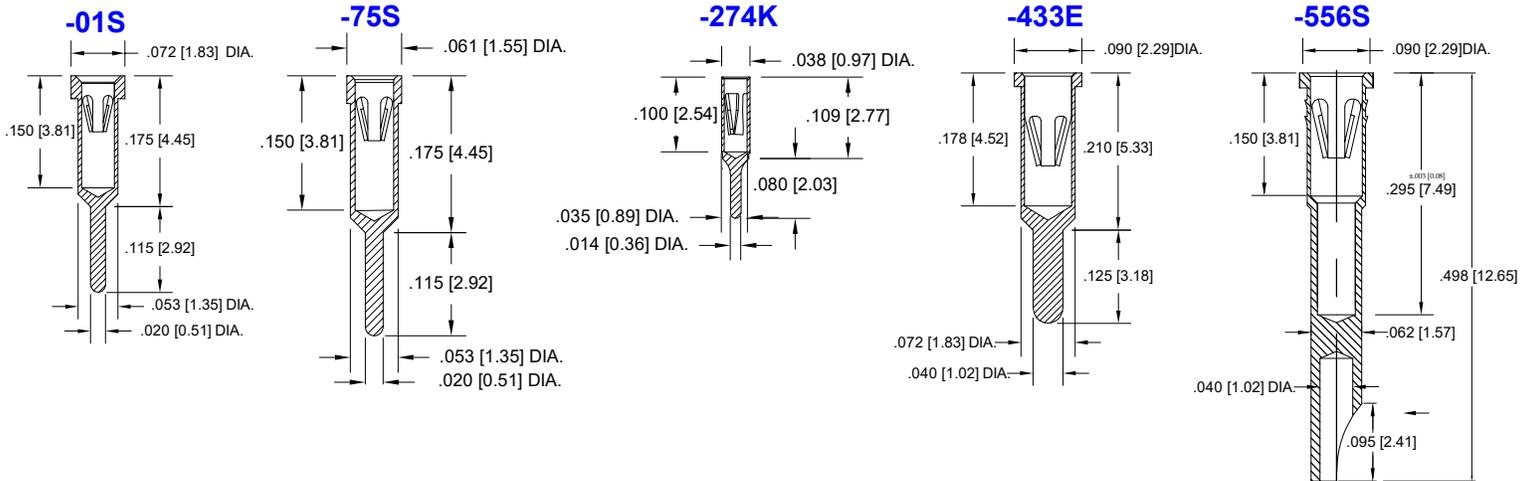
Topica eagleyard *Continued*

Socket Terminal Details

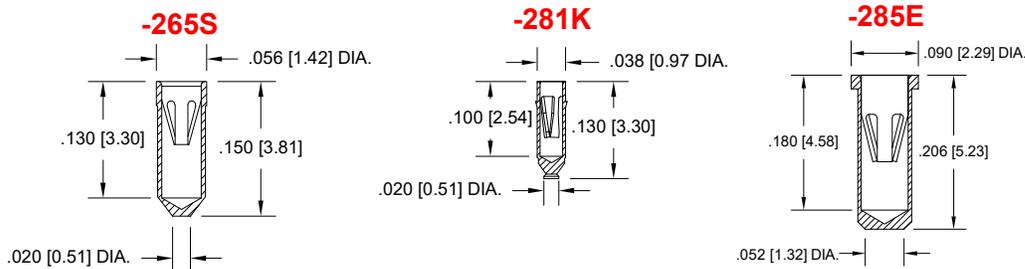
Cross Section View Shown Units: in [mm]

Other Terminal Layouts and Configurations available

THRU HOLE OPTION



SURFACE MOUNT OPTION



Technical Information

Material:

Insulator: Hi-Temp UL 94V-O
Terminal: Brass, per ASTM-B16
Contact: BeCu, Per ASTM-B194

Plating: RoHS COMPLIANT

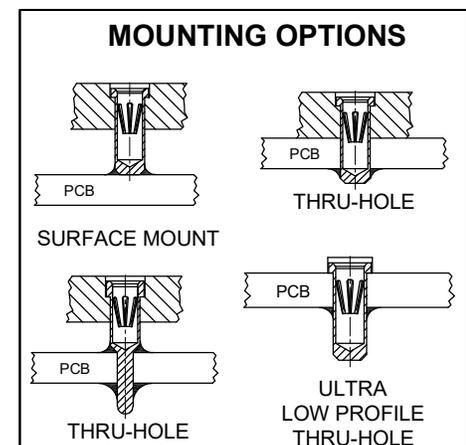
R27 TERMINAL: GOLD / CONTACT: GOLD

R17 TERMINAL: TIN / CONTACT: GOLD

OTHER PLATINGS AVAILABLE

Terminal Acceptance and Forces

Thru Hole Terminals				Surface Mount Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	Surface Mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
-01S	Ø.018 [Ø0.46]	9.0 oz Avg.	2.0 oz Min	-	-	-	-
-433E	Ø.040 [Ø1.02]	36.0 oz Max.	3.9 oz Min	-285E	Ø.040 [Ø1.02]	36.0 oz Max.	3.9 oz Min
-75S	Ø.018 [Ø0.46]	9.0 oz Avg.	2.0 oz Min	-265S	Ø.018 [Ø0.46]	9.0 oz Avg.	2.0 oz Min
-274K	Ø.018 [Ø0.46]	1.0 oz Avg.	0.5 oz Min	-281K	Ø.018 [Ø0.46]	1.0 oz Avg.	0.5 oz Min



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"ANDON PROPRIETARY INFORMATION"
RoHS Compliant

*Sockets are not drawn to scale Topica eagleyard 02/01/2024

For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies designed to your pin layout.



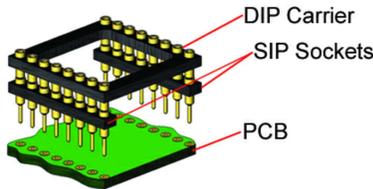
Phase 2:
Place carrier assemblies onto PCB; run through your soldering process.



Phase 3:
Remove carrier and plug in your device; discard carrier.

DIP

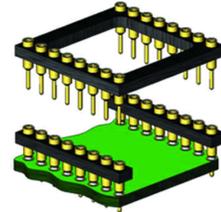
Before Soldering



During Soldering



After Soldering

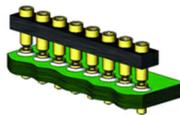


ULTRA-LOW PROFILE SIP

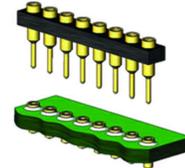
Before Soldering



During Soldering

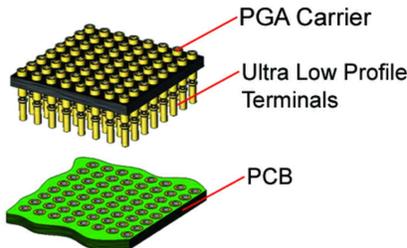


After Soldering

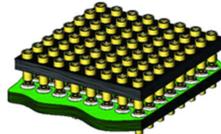


ULTRA-LOW PROFILE PGA

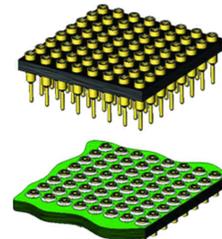
Before Soldering



During Soldering

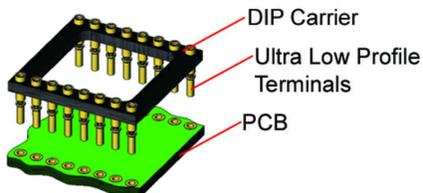


After Soldering

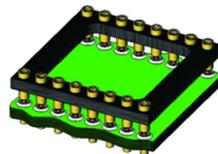


ULTRA LOW PROFILE DIP

Before Soldering



During Soldering



After Soldering

